



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR PowerPAIR® 3 x 3					
STRESS	SAMPLE SIZE	DEVICE HR./CYC	CONDITION	TOTAL FAILS	FAIL PERCENTAGE
HAST	330	33 000	130 °C, 85 % RH	0	0.00
Pressure Pot	165	15 840	121°, 15 PSIG	0	0.00
Solder DUNK	55	165	260 °C, 10 s	0	0.00
Solderability	15	120	883 M2003	0	0.00
Temp. Cycle	165	163 500	- 65 °C to 150 °C	0	0.00